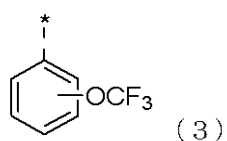
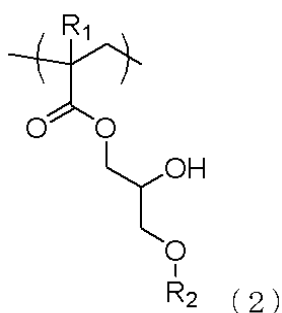
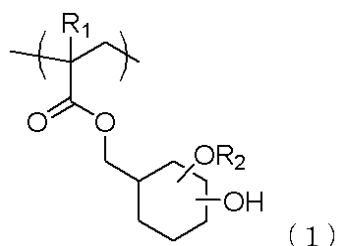


TITLE OF INVENTION: COMPOSITION FOR FORMING ORGANIC FILM,
METHOD FOR FORMING ORGANIC FILM, PATTERNING PROCESS, MONOMER,
AND POLYMER

ABSTRACT

The present invention is a composition for forming an organic film, containing: a resin and/or compound (A) for forming an organic film; a polymer (B) having a repeating unit represented by the following general formula (1) and/or (2); and a solvent (C). This can provide: a composition for forming an organic film which is excellent in film-formability (in-plane uniformity) on a substrate (wafer) and filling property, can suppress humps in an EBR process, and allows an excellent process margin when used for an organic underlayer film for a multilayer resist; a method for forming an organic film, using the composition; a patterning process using the composition; a monomer; and a polymer.



[FIG. 1]